

ABSTRACTMETHOD FOR DISPENSING ADHESIVE ON A CIRCUIT-BOARD CARRIERMEMBER AND CIRCUIT-BOARD PROVIDED THEREBY

An adhesive-dispensing method applies a pattern of adhesive onto a circuit-board carrier such that any discontinuities in the pattern, i.e. starting-points, end-points or turning-points, are outside a footprint of a pair of substrates or MMICs intended to be attached, adjacent each other and spaced apart, to the circuit-board, and in particular outside such footprint in the area of transition between one substrate/MMIC and the other. The adhesive is preferably applied in straight lines and in a direction substantially transverse to the direction of transition between the two substrates/MMICs.

(Fig 5)

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